

Passively aligned fiber-coupling of planar integrated waveguides

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SPPL-Event: Miniaturized Photonic Packaging – Alpnach

Acknowledgement

- Research in cooperation with vario-optics ag, Heiden AR

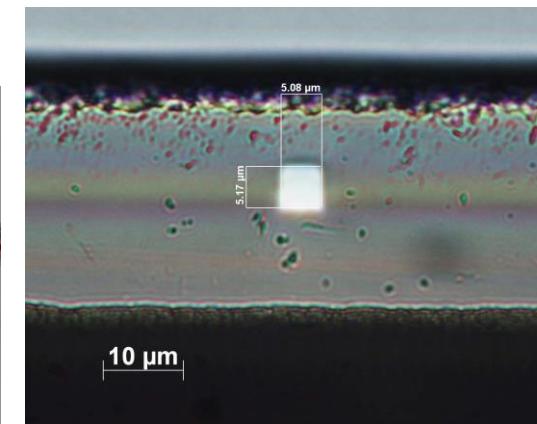


- Funded by KTI – PFEN-NM 16259.2
- Research published:

Kremmel J., Lamprecht T., Crameri N., Michler M.; «Passively aligned multichannel fiber-pigtailing of planar integrated optical waveguides» Opt. Eng. 0001;56(2):026115.
doi:10.1117/1.OE.56.2.026115.

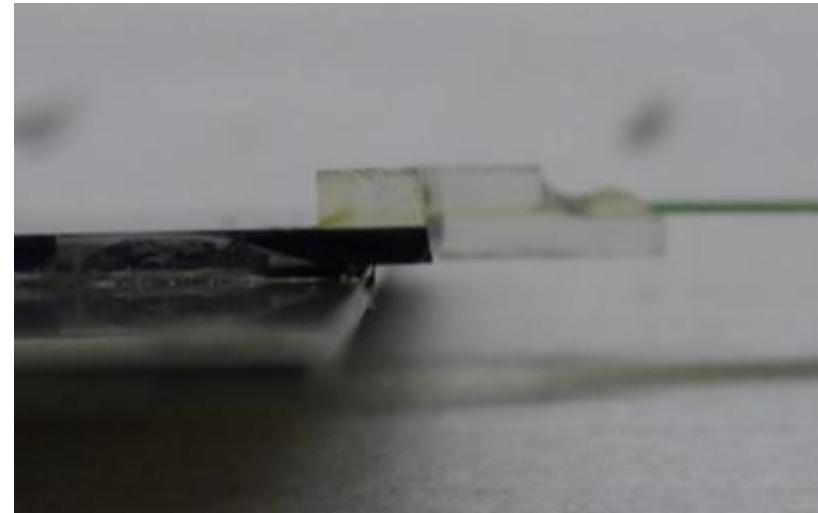
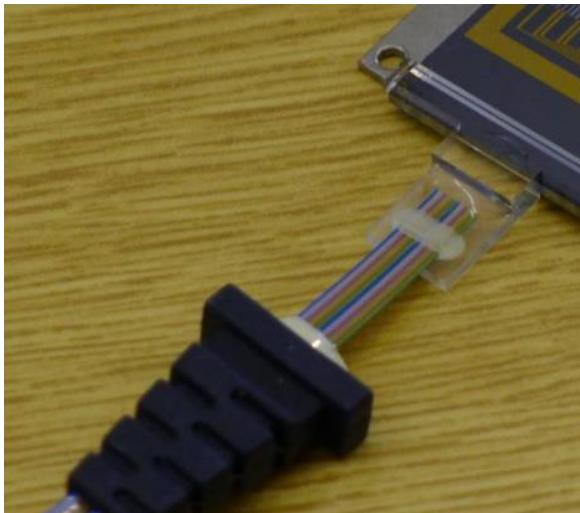
Motivation

- Fiber coupling of integrated optical systems is important:
 - Communication over long distances
 - Coupling to sources
 - Interlinking of PLCs (Planar Lightwave Circuits)
- Properties
 - High integration density of PLCs → Fiber-Arrays
 - Facet-coupling of dielectric waveguides with low index-contrast is most efficient (in terms of IL, space consumption etc.)
 - Small surface area on the facets of the fibers and waveguide-boards limits the durability of a facet joint



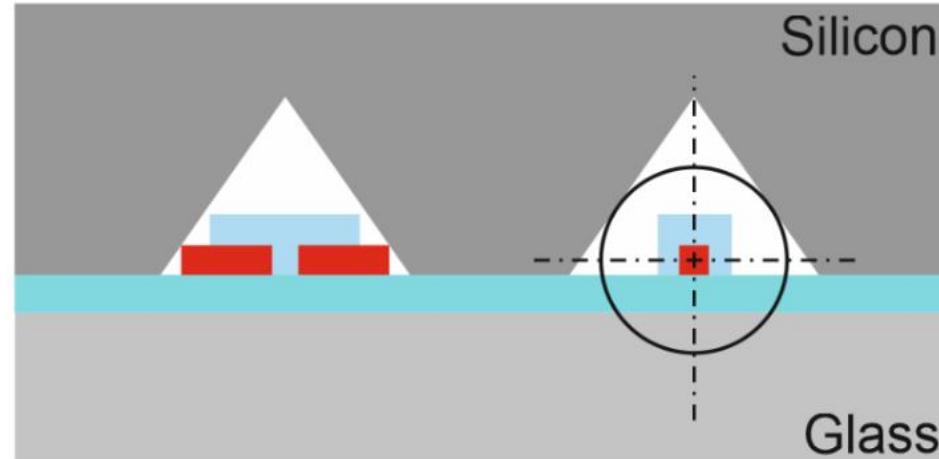
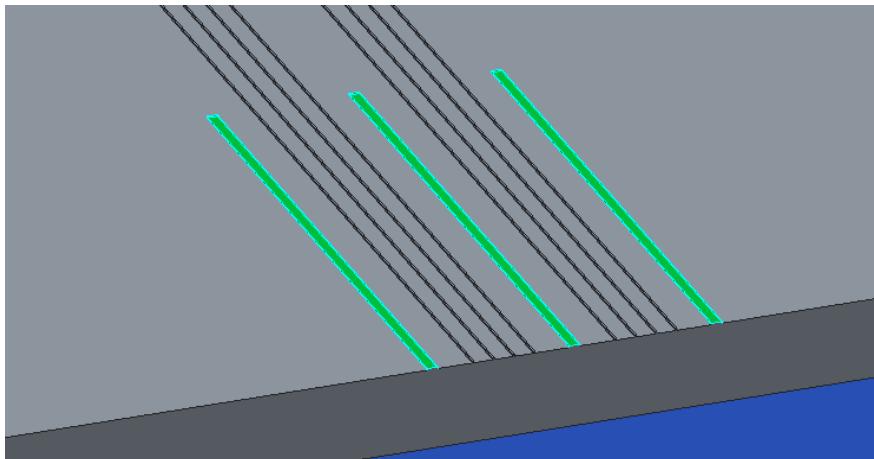
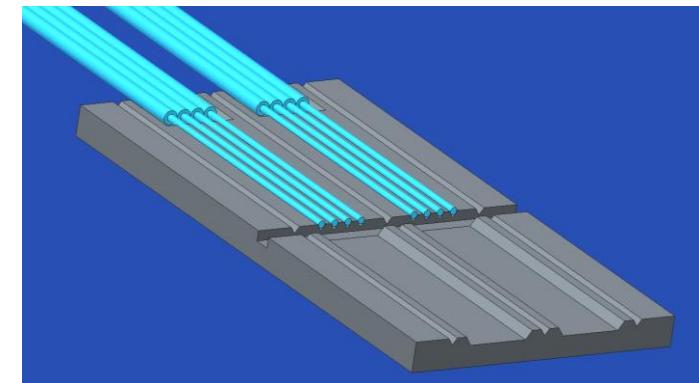
State of the Art

- Active alignment of fiber-arrays and adhesive bonding
 - Apply glass-blocks to enlarge the bonding surface
 - Polishing the facet
 - Active alignment & bonding using and UV-curing adhesive
- Automation difficult & device specific (high volume)
→ Fiber-coupling is a significant cost contributor



Approach

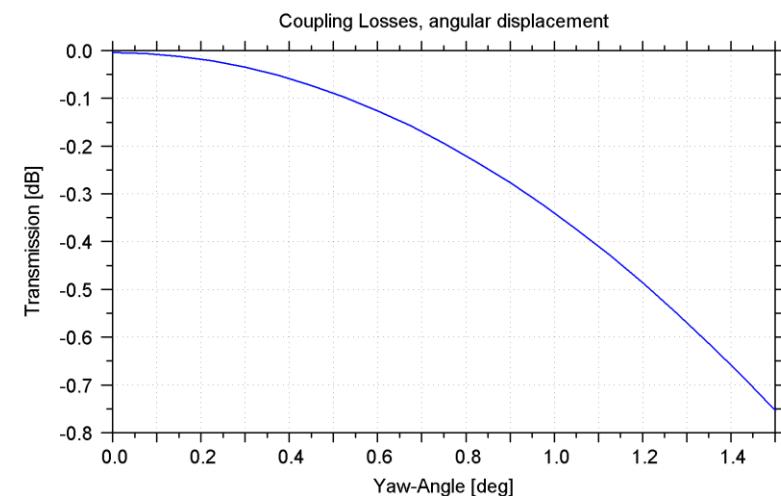
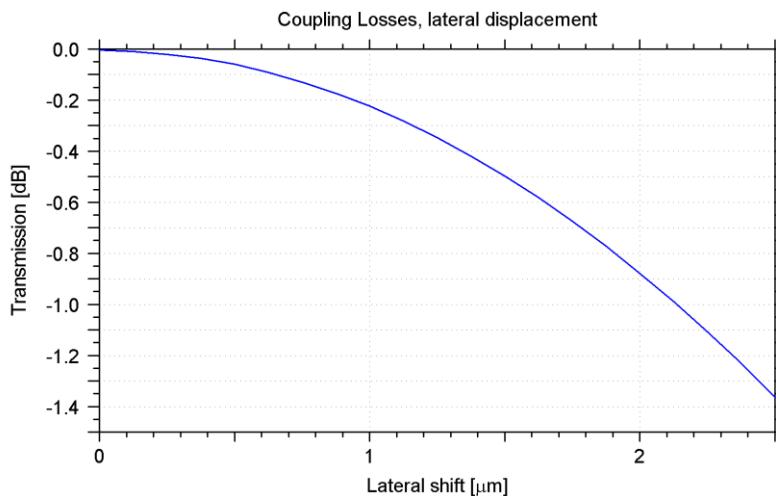
- Goal: passively aligned multi-channel fiber coupling of PLCs
- Silicon-element with V-Grooves
 - V-Grooves as Fiber-Holder
 - V-Grooves as alignment feature
- Coupling interface on PLC board
 - Structured cladding
 - Core structures as alignment feature



Source: Kremmel et al., Opt. Eng. 56 (2) 2017

Coupling characteristics

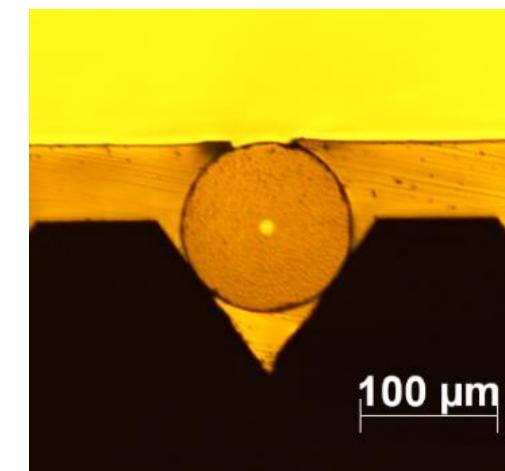
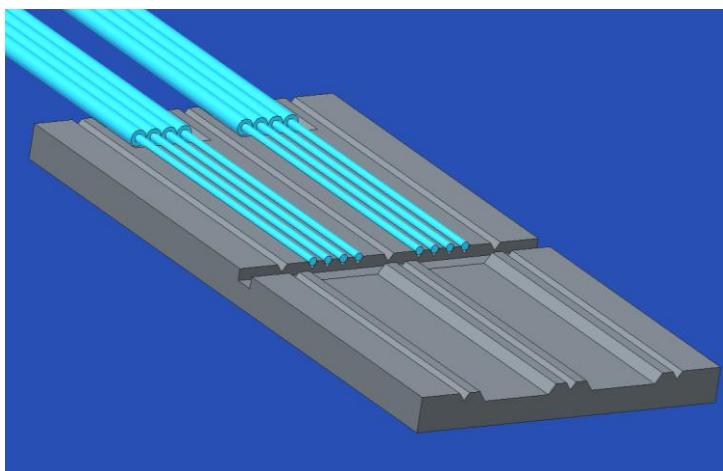
- Lateral and angular displacement – coupling efficiency
 - Waveguide: $5\mu\text{m} \times 5\mu\text{m}$, $\Delta n = 0.006$



- Accuracy, accepting a displacement loss of 0.5dB:
 - Lateral: $<1.5\mu\text{m}$
 - Axial: $<50\mu\text{m}$
 - Angular: $<1.2^\circ$
 - Losses by Mode-Mismatch: 0.18dB

Silicon-Element

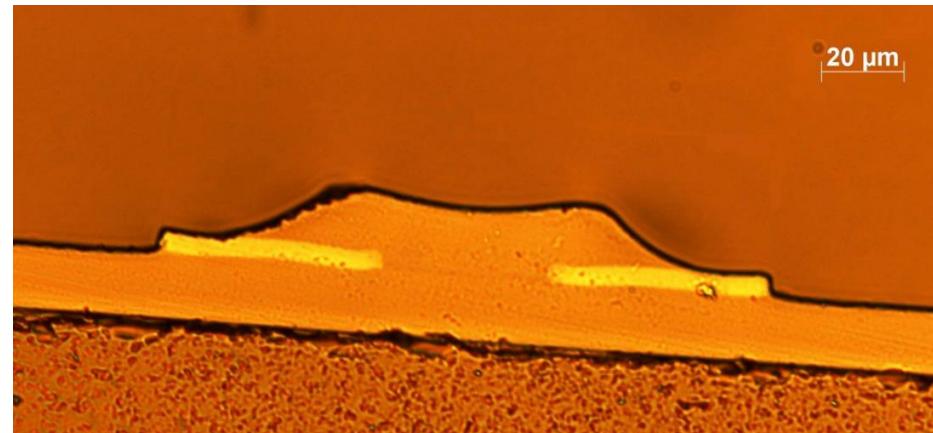
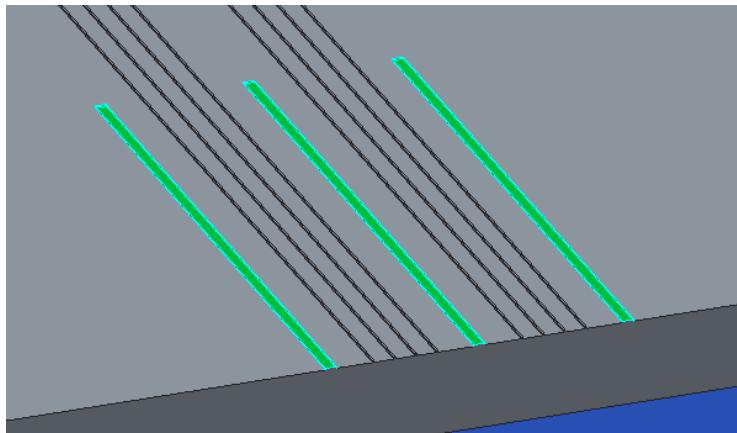
- Precise Etching of V-Grooves in Silicon using KOH
 - Slow etching {111}-Planes for high accuracy
 - 8 Grooves for fibers
 - 3 Grooves as alignment feature
 - Large bonding area: minimal angular deviation, adhesion



- Assembly
 - Adhesive bonding of the fibers
 - cut and polish the fibers using a wafer dicer
 - all facets in one plane, <30nm RMS

Coupling Interface PLC

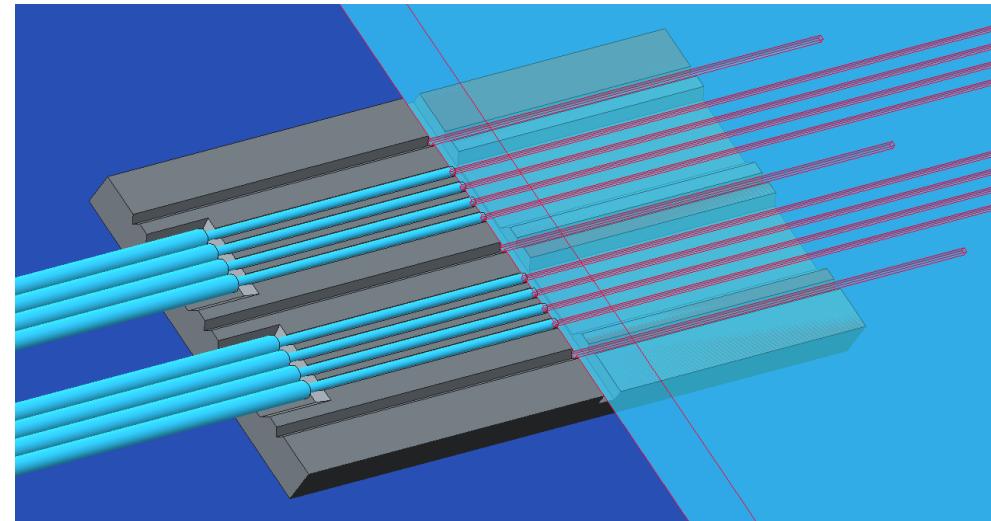
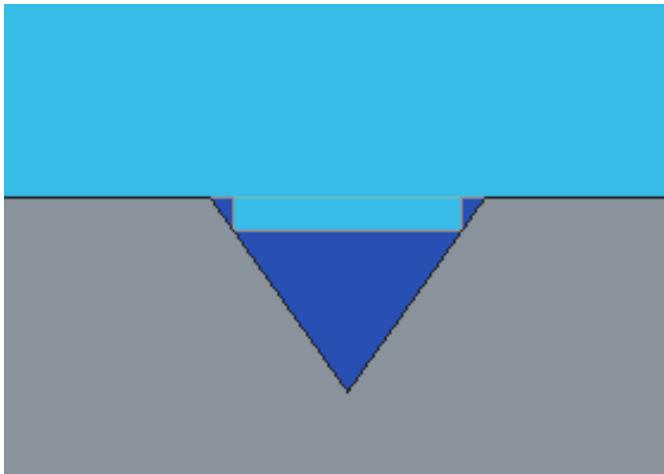
- Waveguides with structured top-cladding
 - Structuring by curing UV-LDI
- Alignment structures corresponding to alignment V-Grooves
 - Alignment features and waveguide-cores in the same process step
 - Maximum position accuracy



→ Assembly using UV-curing adhesive

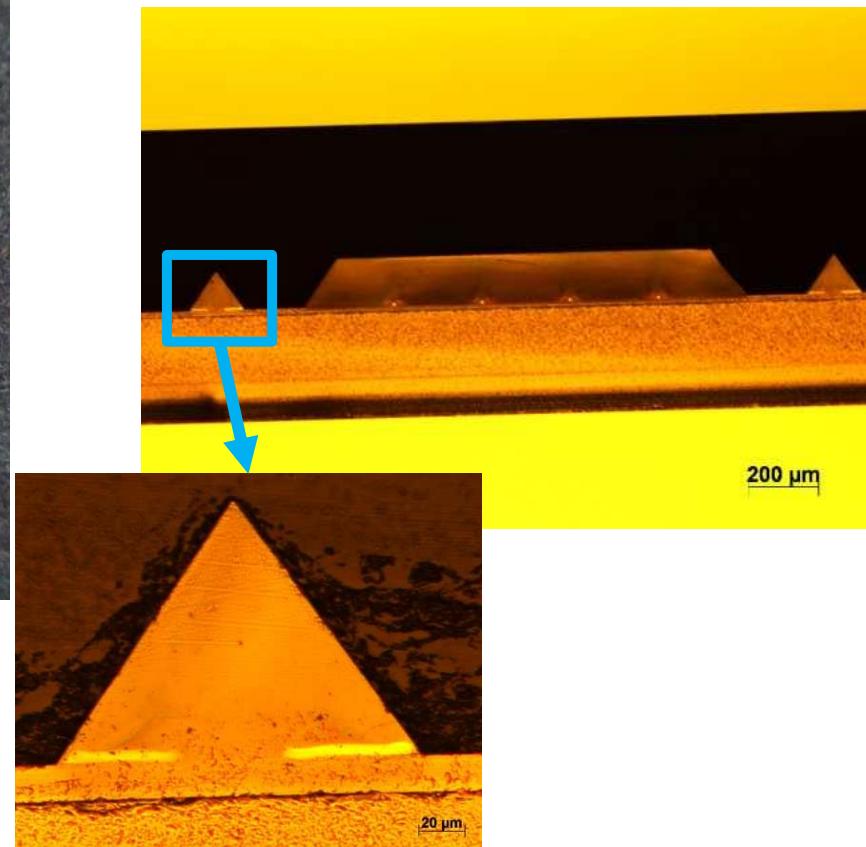
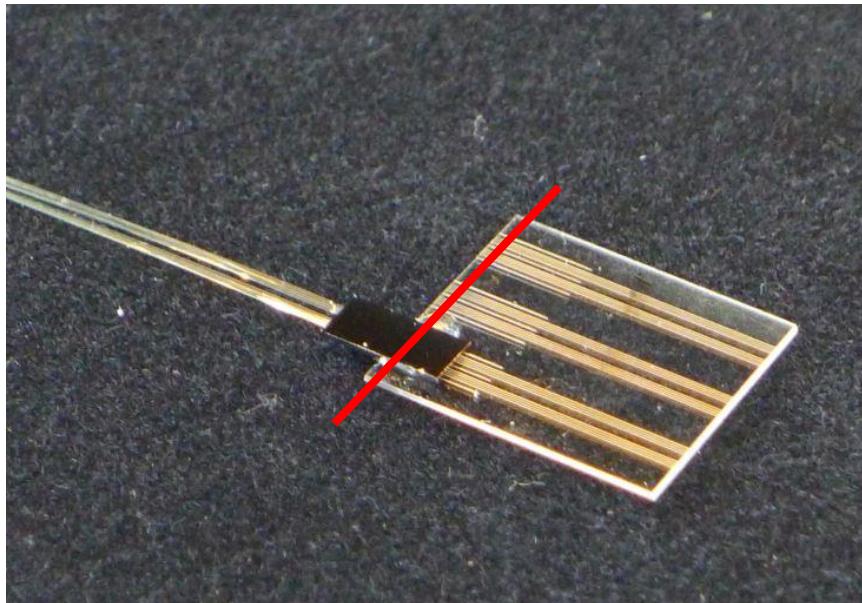
Assembly I

- Application of the silicon fiber-ribbon onto the PLC-Board
 - Alignment structures fit to V-Grooves and provide precise lateral alignment
 - Axial alignment: facets act as stop
- Mounting using UV-curing adhesive
 - Adhesive as index-matching agent



Assembly II

- Microscopy analysis of the Assembly
 - Cross-sections to investigate alignment



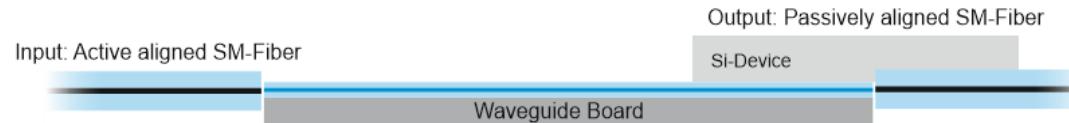
Optical Characterization

- Measurement of the Coupling Loss
 - Compare passively coupled WGs and reference WGs
 - Reference Measurement:



→ Measure light transmitted through WG

- Measurement passive coupling:



→ Measure light transmitted through WG & coupled into SM-Fiber

Results

$T_{Ref} = -1.69 \text{ dB}$

$T_{Ribbon} = -1.92 \text{ dB}$

→ Losses by SM-Coupling (CL): 0.23 dB

Losses due to Misalignment: 0.05 dB

- CL – Transition Loss: 0.23dB - 0.18dB

Scattering Losses: 0.22 dB

- Cut-Back Measurement

→ Total Coupling Losses/Interface: (0.45 +/- 0.20) dB

- Transition Loss + Misalignment + Scattering

Results II

- Climate Tests:
 - Thermal Cycling: -30 – 70°C, 10 times
 - Transmission remains unchanged on all channels
 - 85/85-Test for 168h:
 - Losses increase by 1.2dB in average
 - Reference Waveguides stable
 - SEM-Analysis of Cross-Sections: delamination of the adhesive in the gap between fiber and waveguide

Conclusions

- Passively aligned coupling of 8 SM-fibers to 8 SM-WGs has been demonstrated successfully
 - Achieved coupling losses are significantly lower than earlier reports
 - Simple assembly: no additional tools necessary (even by hand)
 - For climate tests → further optimization of assembly process
- Only standard MEMS resp. MOEMS fabrication and packaging processes have been applied
 - Si-etching in KOH
 - Adhesive bonding
 - Wafer dicing